



## Product/Process Change Notice - PCN 13\_0070 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

**PCN Title:** ADIS16060 PCB Plating Change

**Publication Date:** 18-Apr-2013

**Effectivity Date:** 17-Jul-2013 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release

### Description Of Change

Change the plating material of the laminate pcb from electroless nickel over gold (ENIG) to nickel/palladium/gold (NiPdAu).

### Reason For Change

Improved adhesion of solder mask layer.

### Impact of the change (positive or negative) on fit, form, function & reliability

No change to performance, dimensions or reliability.

### Product Identification *(this section will describe how to identify the changed material)*

Estimated datecode 1326 or higher.

### Summary of Supporting Information

Qualification has been performed to validate no change to the device's Moisture Sensitivity Level (MSL).

### Supporting Documents

**Attachment 1: Type:** Qualification Report Summary

ADI\_PCN\_13\_0070\_Rev\_-\_13\_0070Qual Summary.docx

**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** PCN\_Americas@analog.com

**Europe:** PCN\_Europe@analog.com

**Japan:** PCN\_Japan@analog.com

**Rest of Asia:** PCN\_ROA@analog.com

**Appendix A - Affected ADI Models**

**Added Parts On This Revision - Product Family / Model Number (2)**

ADIS16060 / ADIS16060PCBZ

ADIS16060 / ADIS16060BCCZ

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	18-Apr-2013	17-Jul-2013	Initial Release

Analog Devices, Inc.

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